AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/612,711 Filing Date: June 30, 2003

Title: THERMAL INTERFACE APPARATUS, SYSTEMS, AND METHODS

Assignee: Intel Corporation

## IN THE ABSTRACT OF THE DISCLOSURE

Please amend the Abstract as follows:

An apparatus and system, as well as fabrication methods therefor, may include a thermal interface material comprised of an array of carbon nanotubes and a buffer layer disposed between the thermal interface material and one of a die or a heat spreader. In some embodiments the carbon nanotubes may be formed above a buffer layer formed above a surface of the heat spreader.